

## AMENDMENTS TO THE CLAIMS

The listing of the claims will replace the previous version, and the listing of the claims:

## LISTING OF THE CLAIMS

1. (cancelled)

2. (currently amended) The method for manufacturing a synthetic resin molding according to claim ~~±~~ 9, wherein the temperature ~~condition~~ is a ~~temperature~~ in a range of 80 to 120°C.

3-5. (cancelled)

6. (currently amended) The method for manufacturing a synthetic resin molding according to claim ~~±~~ 9, wherein the base resin is an olefin resin with a melt flow rate (MFR) of 30 to 90 g/10 min.

7-8. (cancelled)

9. (new) A method for manufacturing a synthetic resin molding, comprising:

affixing a binder resin to thermal expansion microcapsules in a temperature such that the thermal expansion microcapsules do not expand to thereby form granulated microcapsules with an average particle diameter of 140-2,870  $\mu\text{m}$ ,

mixing the granulated thermal expansion microcapsules with a base resin, and

molding a mixture of the granulated thermal expansion microcapsules and the base resin in a mold.

10. (new) The method for manufacturing a synthetic resin molding according to claim 9, wherein said base resin has a pellet shape.

11. (new) The method for manufacturing a synthetic resin molding according to claim 9, wherein said thermal expansion microcapsules are granulated at a temperature between 80 and 120 °C such that low boiling point hydrocarbon containing in the thermal expansion microcapsules does not expand.

12. (new) The method for manufacturing a synthetic resin molding according to claim 11, wherein each of said thermal expansion microcapsules is formed of said low boiling point hydrocarbon coated with an acrylic resin and has an average diameter of 20-35  $\mu\text{m}$ .

13. (new) The method for manufacturing a synthetic resin molding according to claim 11, wherein said thermal expansion microcapsules are granulated without pre-expansion.